



Material Content Data Sheet



Sales Product Name		BTS117		Issued		25. September 2017		
MA#		MA001017900						
Package		PG-TO220-3-1		Weight*		2018.99 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.361	0.17	0.17	1665	1665
leadframe	inorganic material	phosphorus	7723-14-0	0.245	0.01		121	
	non noble metal	iron	7439-89-6	0.816	0.04		404	
	non noble metal	copper	7440-50-8	815.335	40.39	40.44	403833	404358
	non noble metal	aluminium	7429-90-5	1.449	0.07	0.07	717	717
wire	non noble metal	aluminium	7429-90-5	1.449	0.07	0.07	717	717
encapsulation	organic material	carbon black	1333-86-4	6.412	0.32		3176	
	inorganic material	antimonytrioxide	1309-64-4	13.407	0.66		6640	
	plastics	brominated resin	-	15.156	0.75		7507	
	plastics	epoxy resin	-	110.754	5.49		54856	
	inorganic material	silicondioxide	60676-86-0	437.185	21.65	28.87	216537	288716
leadfinish	non noble metal	tin	7440-31-5	21.462	1.06	1.06	10630	10630
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1	
	non noble metal	nickel	7440-02-0	0.244	0.01	0.01	121	122
glue	plastics	Polyimide	26023-21-2	0.157	0.01	0.01	78	78
solder	non noble metal	tin	7440-31-5	0.055	0.00		27	
	noble metal	silver	7440-22-4	0.069	0.00		34	
	non noble metal	lead	7439-92-1	2.649	0.13	0.13	1312	1373
heatspreader	inorganic material	phosphorus	7723-14-0	0.177	0.01		88	
	non noble metal	iron	7439-89-6	0.590	0.03		292	
	non noble metal	copper	7440-50-8	589.466	29.20	29.24	291961	292341
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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